

MOS FIELD EFFECT TRANSISTOR 2SK3366

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The 2SK3366 is N-Channel MOS Field Effect Transistor designed for DC/DC converter application of notebook computers.

FEATURES

· Low on-resistance

 $R_{DS(on)1} = 21 \text{ m}\Omega \text{ (MAX.) (V}_{GS} = 10 \text{ V, I}_{D} = 10 \text{ A)}$ $R_{DS(on)2} = 33 \text{ m}\Omega \text{ (MAX.) (V}_{GS} = 4.5 \text{ V, I}_{D} = 10 \text{ A)}$

 $R_{DS(on)3} = 43 \text{ m}\Omega \text{ (MAX.) (V}_{GS} = 4.0 \text{ V, I}_{D} = 10 \text{ A)}$

- Low Ciss : Ciss = 730 pF (TYP.)
- · Built-in gate protection diode

ORDERING INFORMATION

PART NUMBER	PACKAGE
2SK3366	TO-251 (MP-3)
2SK3366-Z	TO-252 (MP-3Z)

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C)

Drain to Source Voltage (V _{GS} = 0 V)	VDSS	30	V
Gate to Source Voltage (VDS = 0 V)	Vgss	±20	V
Drain Current (DC)	ID(DC)	±20	Α
Drain Current (Pulse) Note	D(pulse)	±80	Α
Total Power Dissipation (Tc = 25 °C)	PT	30	W
Total Power Dissipation (T _A = 25 °C)	PT	1.0	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	-55 to + 150	°C

Note PW \leq 10 μ s, Duty cycle \leq 1 %

THERMAL RESISTANCE

Channel to case Thermal Resistance	Rth(ch-C)	4.17	°C/W
Channel to ambient Thermal Resistance	Rth(ch-A)	125	°C/W

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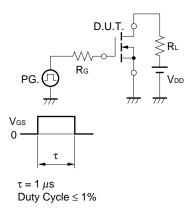


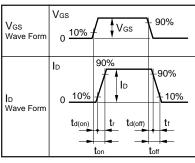
ELECTRICAL CHARACTERISTICS (TA = 25 °C)

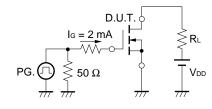
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	R _{DS(on)1}	V _{GS} = 10 V, I _D = 10 A		17.2	21	mΩ
	R _{DS(on)2}	V _{GS} = 4.5 V, I _D = 10 A		26	33	mΩ
	RDS(on)3	V _{GS} = 4.0 V, I _D = 10 A		33	43	mΩ
Gate to Source Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	1.5	2.0	2.5	٧
Forward Transfer Admittance	yfs	V _{DS} = 10 V, I _D = 10 A	5	10		S
Drain Leakage Current	Ipss	V _{DS} = 30 V, V _{GS} = 0 V			10	μА
Gate to Source Leakage Current	Igss	V _{GS} = ±20 V, V _{DS} = 0 V			±10	μА
Input Capacitance	Ciss	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		730		pF
Output Capacitance	Coss			250		pF
Reverse Transfer Capacitance	Crss			120		pF
Turn-on Delay Time	t _{d(on)}	I _D = 10 A, V _{GS} = 10 V, V _{DD} = 15 V,		28		ns
Rise Time	tr	$R_G = 10 \Omega$		420		ns
Turn-off Delay Time	t _{d(off)}			47		ns
Fall Time	t _f			64		ns
Total Gate Charge	Q _G	I _D = 20 A, V _{DD} = 24 V, V _{GS} = 10 V		15		nC
Gate to Source Charge	Qgs			2.8		nC
Gate to Drain Charge	QgD			4.1		nC
Body Diode forward Voltage	V _{F(S-D)}	I _F = 20 A, V _{GS} = 0 V		1.0		V
Reverse Recovery Time	trr	I _F = 20 A, V _{GS} = 0 V		30		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		26		nC

TEST CIRCUIT 1 SWITCHING TIME

TEST CIRCUIT 2 GATE CHARGE

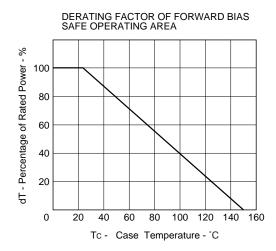




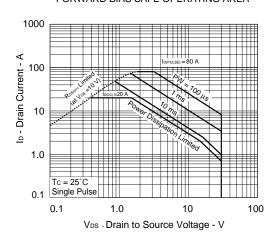




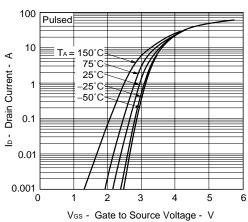
TYPICAL CHARACTERISTICS (TA = 25 °C)

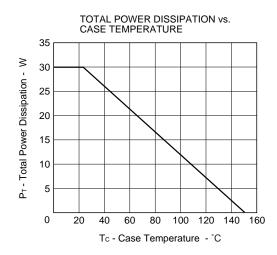


FORWARD BIAS SAFE OPERATING AREA

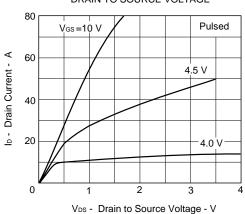


FORWARD TRANSFER CHARACTERISTICS

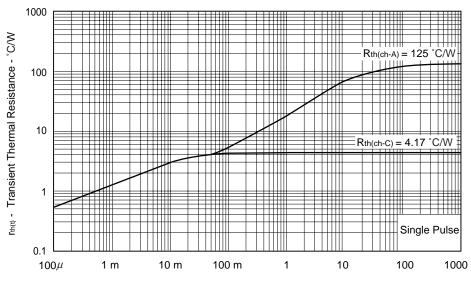




DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE

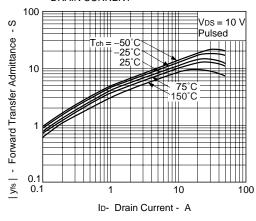


TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

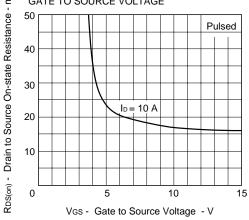


PW - Pulse Width - s

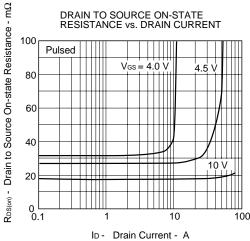




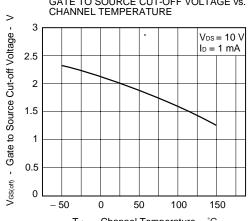
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE ДШ



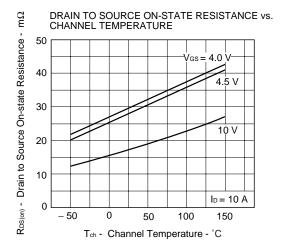
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

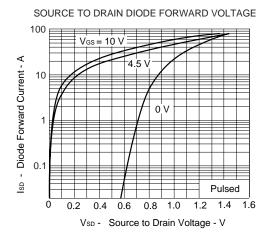


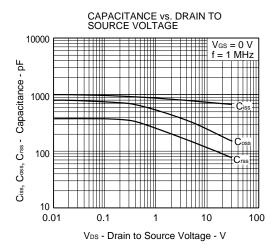
GATE TO SOURCE CUT-OFF VOLTAGE vs.

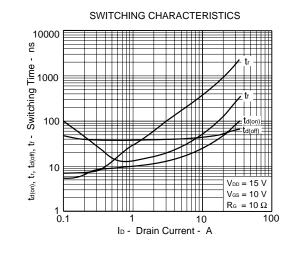


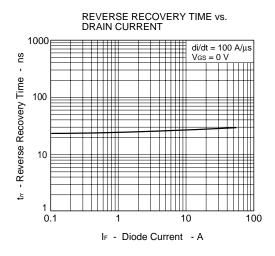
Tch - Channel Temperature - °C

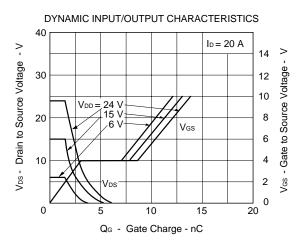








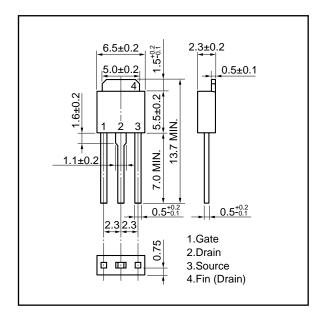




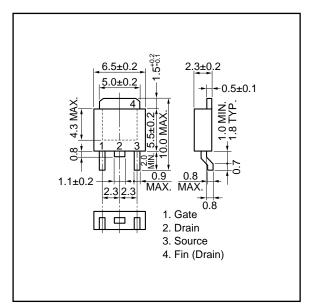


PACKAGE DRAWINGS (Unit: mm)

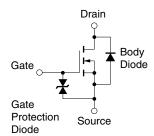
★ 1) TO-251 (MP-3)



2) TO-252 (MP-3Z)



EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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